

ABSTRACT

A semiconductor packaging method includes: fixing a die and a conductive post to a carrier board, the die provided with a bond pad on a front side thereof and an inductance element on a back side thereof, the die oriented so that the front side faces the carrier board, the conductive post located beside the die; forming a plastic encapsulation layer on the carrier board, the plastic encapsulation layer encapsulating the die, the inductance element and the conductive post, with at least part of the inductance element and an end face of a first end of the conductive post being both exposed from the plastic encapsulation layer; forming a first conductive trace on a surface of the plastic encapsulation layer close to the back side of the die, the first conductive trace connecting a first electrical connection point of the inductance element to the first end of the conductive post; removing the carrier board; and forming a second conductive trace on a surface of the plastic encapsulation layer close to the front side of the die, the second conductive trace connecting a bond pad on the die to a second end of the conductive post. Also disclosed is a semiconductor packaging structure.